PCN Number:		20180802003		PCN Date:	Au	August 08, 2018					
Title: Datasheet for LSF0108-Q1											
Cu	stom	er Contact:	PCN Manag	<u>er</u>			Dej	ot:	Quality Services		
Change Type:											
		mbly Site			Design				Bump Site		
Assembly Process				\square	Data Sheet				Bump Material		
Assembly Materials					Part number change	ļĻ			Bump Process		
Mechanical Specificatio					Test Site				Fab Site		
Packing/Shipping/Labeling			'Labeling		Test Process	┥┝			Fab Materials		
								Wafer	Fab Process		
Notification Details											
Description of Change:											
Texas Instruments Incorporated is announcing an information only notification.											
The product datasheet(s) is being updated as summarized below.											
The following change history provides further details.											
LSF0108-Q1											
INSTRUMENTS SDLS967C - MAY 2016 - REVISED JULY 2018											
Changes from Revision B (June 2016) to Revision C Page											
Changed Thermal Information values											
The datasheet number will be changing.											
Device Family					Change From:	:		Change To:			
LSF0108-Q1					SDLS967B	SDLS967B			SDLS967C		
These changes may be reviewed at the datasheet links provided.											
http://www.ti.com/product/LSF0108-Q1											
Reason for Change:											
To accurately reflect device characteristics.											
Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):											
No anticipated impact. This is a specification change announcement only. There are no changes to the actual device.											
Changes to product identification resulting from this PCN:											
None.											
Product Affected:											
-		8QPWRQ1									
For questions regarding this notice, e-mails can be sent to the regional contacts shown below											

or your local Field Sales Representative.

E-Mail
PCNAmericasContact@list.ti.com
PCNEuropeContact@list.ti.com
PCNAsiaContact@list.ti.com
PCNJapanContact@list.ti.com
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